



US00D890125S

(12) **United States Design Patent**
Feng

(10) **Patent No.:** **US D890,125 S**

(45) **Date of Patent:** **** Jul. 14, 2020**

(54) **EARPHONE**

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(**) Term: **15 Years**

(21) Appl. No.: **29/731,263**

(22) Filed: **Apr. 14, 2020**

(51) **LOC (12) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/205; D14/223**

(58) **Field of Classification Search**
USPC D14/205, 223; D24/174; 128/865;
381/380, 381, 370; 455/90.3, 575.1,
455/569.1
CPC H04R 1/1016; H04R 1/105; H04R 1/10;
H04R 1/1066; H04R 5/1033; H04R
5/0335; H04R 1/1041; H04R 1/1008;
H04R 5/033

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

2,641,327	A *	6/1953	Balmer	H04R 1/105 181/129
2,875,543	A *	3/1959	Sylvester	D06Q 1/00 428/30
2,958,148	A *	11/1960	Sylvester	B44F 3/00 428/30
D375,959	S *	11/1996	Davis	D14/206
D447,743	S *	9/2001	Ma	D14/223
D460,436	S *	7/2002	Bjorklund	D14/205
D469,422	S *	1/2003	Nguyen	D14/205
D470,129	S *	2/2003	Hlas	D14/205
D474,178	S *	5/2003	Eroma	D14/205
D498,227	S *	11/2004	Dyer	D14/205
D501,196	S *	1/2005	Dyer	D14/205
D504,672	S *	5/2005	Hirano	D14/205

D508,495	S *	8/2005	Bone	D14/203.7
D510,085	S *	9/2005	Suzuki	D14/223
D510,575	S *	10/2005	Leong	D14/205
D512,991	S *	12/2005	Yano	D14/223
D515,069	S *	2/2006	Naito	D14/205
D518,816	S *	4/2006	Naito	D14/205
D526,313	S *	8/2006	Murray	D14/223
D542,267	S *	5/2007	Cha	D14/206
D543,968	S *	6/2007	Wong	D14/205
D575,772	S *	8/2008	Schultz	D14/206
D584,283	S *	1/2009	Soetejo	D14/205

(Continued)

FOREIGN PATENT DOCUMENTS

EM	004596161-0001	*	1/2018
EM	006910618-0001	*	9/2019

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(57) **CLAIM**

The ornamental design for an earphone, as shown and described.

DESCRIPTION

FIG. 1 is a front and top perspective view of an earphone, showing my new design;

FIG. 2 is a rear and bottom perspective view thereof;

FIG. 3 is a front elevational view thereof;

FIG. 4 is a rear elevational view thereof;

FIG. 5 is a left side elevational view thereof;

FIG. 6 is a right side elevational view thereof;

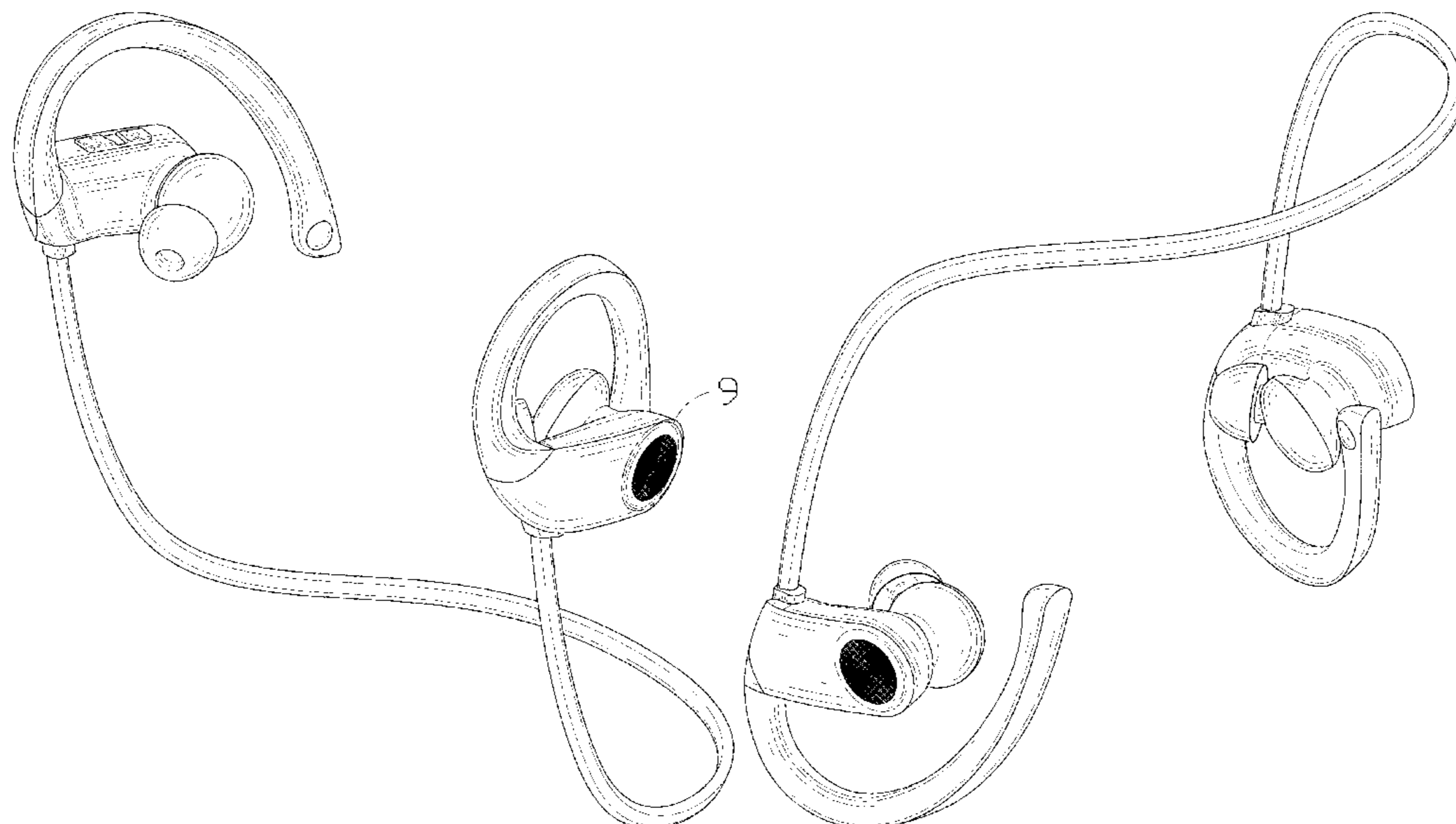
FIG. 7 is a top plan view thereof;

FIG. 8 is a bottom plan view thereof; and,

FIG. 9 is an enlarged view of a portion indicated in FIG. 1.

The broken lines in the figures illustrate portions of the earphone that form no part of the claimed design. The dash dot dash lines in FIGS. 1 and 9 are for the purpose of depicting the cut line of the enlarged view and form no part of the claim.

1 Claim, 9 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

D593,075 S *	5/2009	Williams	D14/223	D741,299 S *	10/2015	Brunner	D14/223
D597,084 S *	7/2009	Gondo	D14/223	D743,946 S *	11/2015	Brunner	D14/223
D599,778 S *	9/2009	Ando	D14/205	D745,862 S *	12/2015	Otani	D14/223
D603,378 S *	11/2009	Paradise	D14/223	D761,770 S *	7/2016	Kanou	D14/206
D603,847 S *	11/2009	Chung	D14/223	D775,610 S *	1/2017	Nakajima	D14/223
D604,722 S *	11/2009	Mistry	D14/223	D778,257 S *	2/2017	Hu	D14/205
D617,778 S *	6/2010	Birger	D14/223	D780,721 S *	3/2017	Brunner	D14/223
D625,297 S *	10/2010	Tseng	D14/223	D782,996 S *	4/2017	Zhu	D14/205
D629,397 S *	12/2010	Hensen	H04R 5/033 D14/223	D795,226 S *	8/2017	Lian	D14/217
D631,470 S *	1/2011	Yoneyama	D14/223	D796,490 S *	9/2017	Lian	D14/217
D635,960 S *	4/2011	Gondo	D14/223	D801,952 S *	11/2017	Lian	D14/223
D639,787 S *	6/2011	Quek	D14/223	D806,684 S *	1/2018	Tsai	D14/223
D640,242 S *	6/2011	Fahrendorff	D14/223	D807,331 S *	1/2018	Morimoto	D14/223
D656,490 S *	3/2012	Birger	D14/223	D810,053 S *	2/2018	Otani	D14/223
8,144,915 B2 *	3/2012	Hankey	H01H 9/0228 381/370	D813,194 S *	3/2018	Loh	D14/205
8,218,808 B2 *	7/2012	Xu	H04R 1/1033 381/370	D829,193 S *	9/2018	Cai	D14/223
8,290,193 B2 *	10/2012	Pang	H04R 1/1033 381/370	10,154,334 B1 *	12/2018	Lin	H04R 1/1041
D671,523 S *	11/2012	Daniel	D14/206	D838,692 S *	1/2019	Fu	D14/223
8,314,354 B2 *	11/2012	Prest	H01H 13/7057 200/406	D843,344 S *	3/2019	Zhu	D14/205
8,447,062 B2 *	5/2013	Lin	H04R 1/1033 381/370	D858,482 S *	9/2019	Ma	D14/205
8,456,864 B2 *	6/2013	Stiehl	H01H 9/0228 361/832	D860,164 S *	9/2019	Lin	D14/205
D685,768 S *	7/2013	Mogili	D14/223	D862,424 S *	10/2019	You	D14/223
D695,275 S *	12/2013	Chee	D14/223	D864,166 S *	10/2019	You	D14/223
D707,659 S *	6/2014	Henning	D14/223	D869,435 S *	12/2019	Sanhua	D14/205
D710,333 S *	8/2014	Davies	H04R 1/10 D14/223	D871,375 S *	12/2019	Meyer	D14/223
D712,382 S *	9/2014	Brunner	D14/223	D872,705 S	1/2020	Dong	
D713,385 S *	9/2014	Burgett	D14/223	D879,067 S *	3/2020	Hu	D14/205
D718,283 S *	11/2014	Thompson	D14/223	D882,545 S *	4/2020	Li	D14/205
D725,637 S *	3/2015	Nakajima	D14/223	D885,370 S *	5/2020	Hu	D14/223
9,031,264 B2 *	5/2015	Yang	H04R 1/1033 381/189	2005/0036644 A1 *	2/2005	Yang	H04R 1/1091 381/384
D734,744 S *	7/2015	Brunner	D14/223	2011/0317865 A1 *	12/2011	Stevinson	H04R 1/1033 381/384
				2014/0072137 A1 *	3/2014	Nelson	H04R 1/1041 381/74
				2014/0119555 A1 *	5/2014	Lu	H04R 25/554 381/74
				2015/0330478 A1 *	11/2015	Grewal	H04R 1/1033 381/384
				2016/0142808 A1 *	5/2016	Monahan	H04R 5/033 381/384
				2017/0105679 A1 *	4/2017	Gil	A61B 5/6815

* cited by examiner

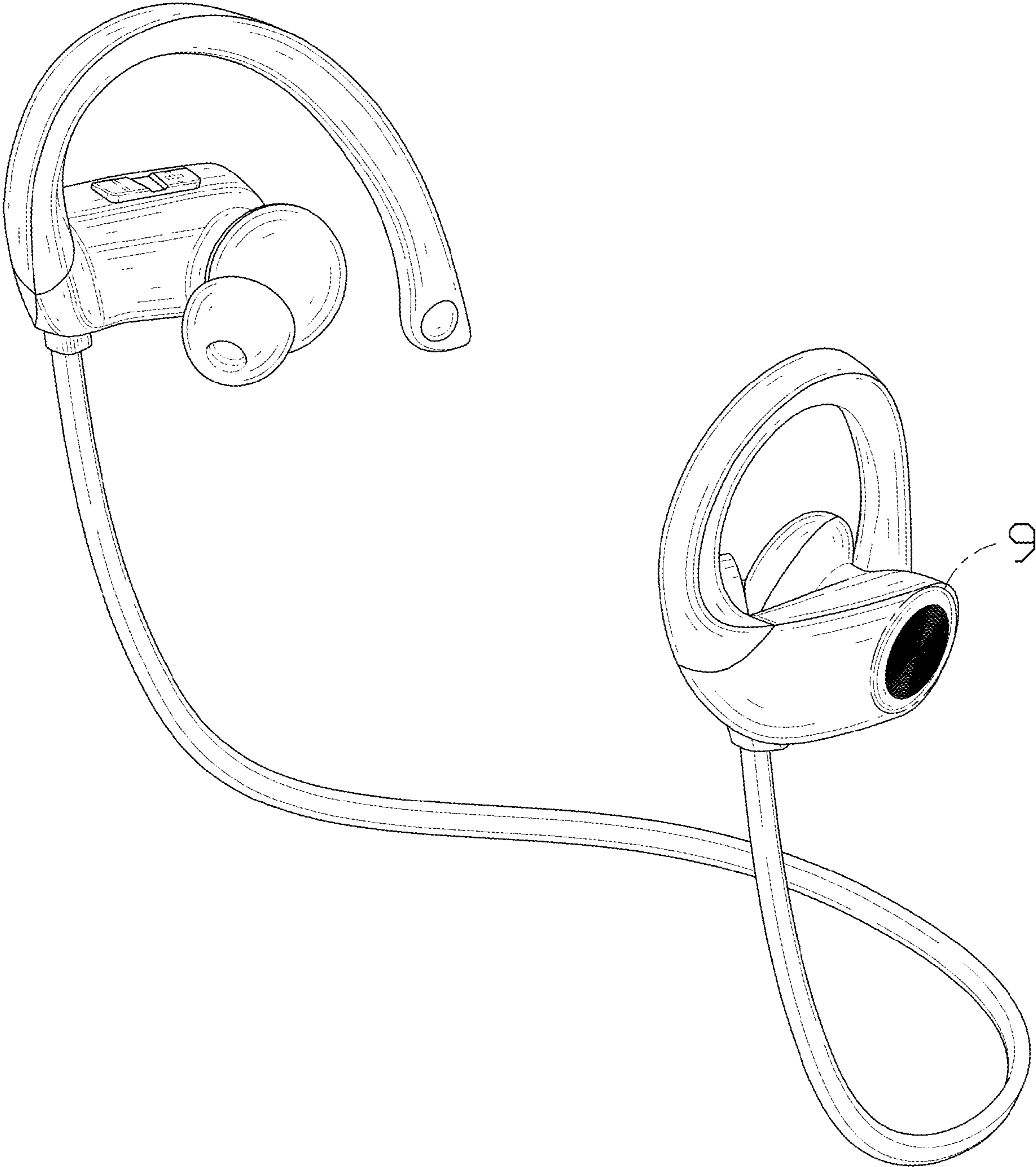


FIG. 1

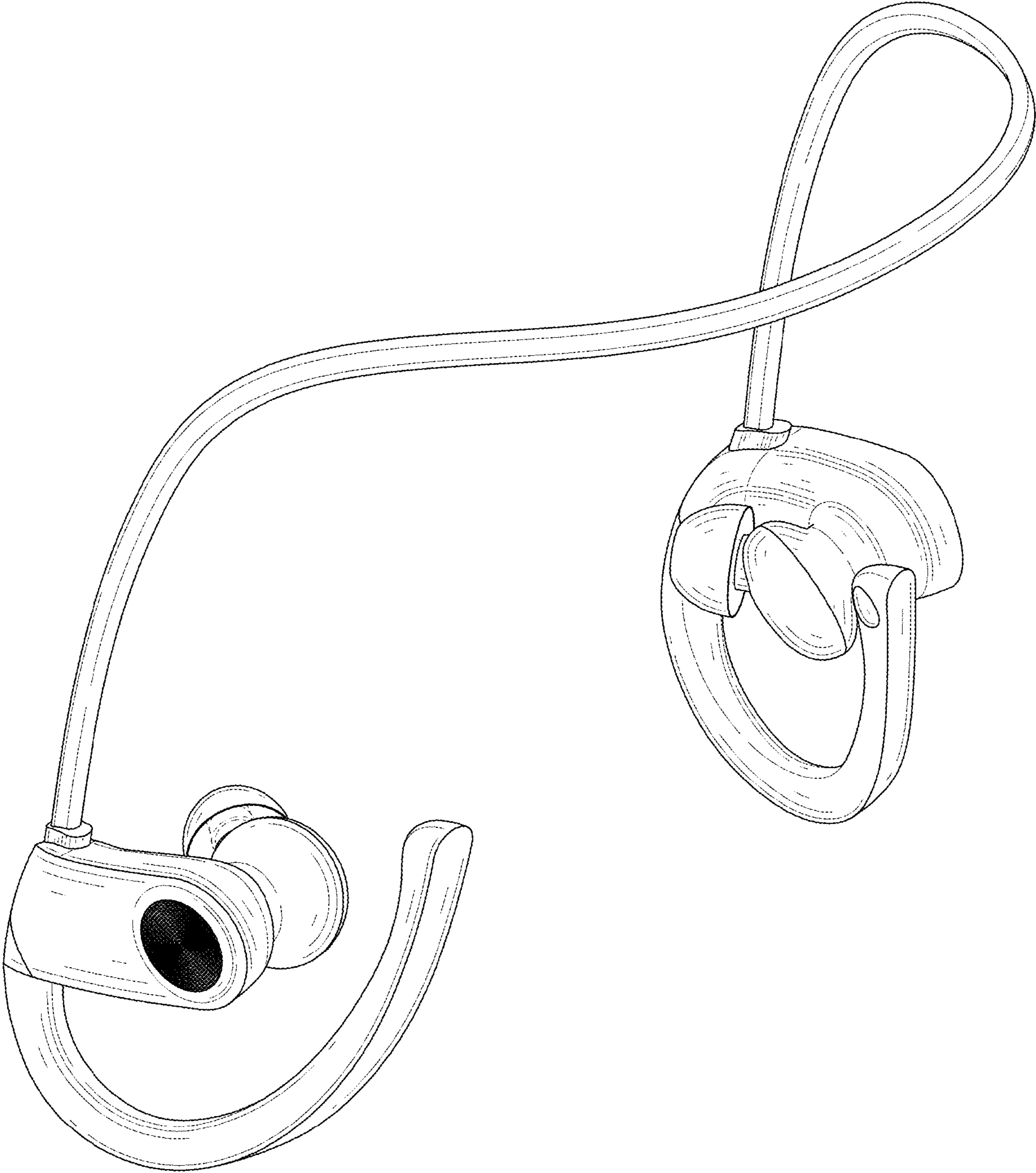


FIG. 2

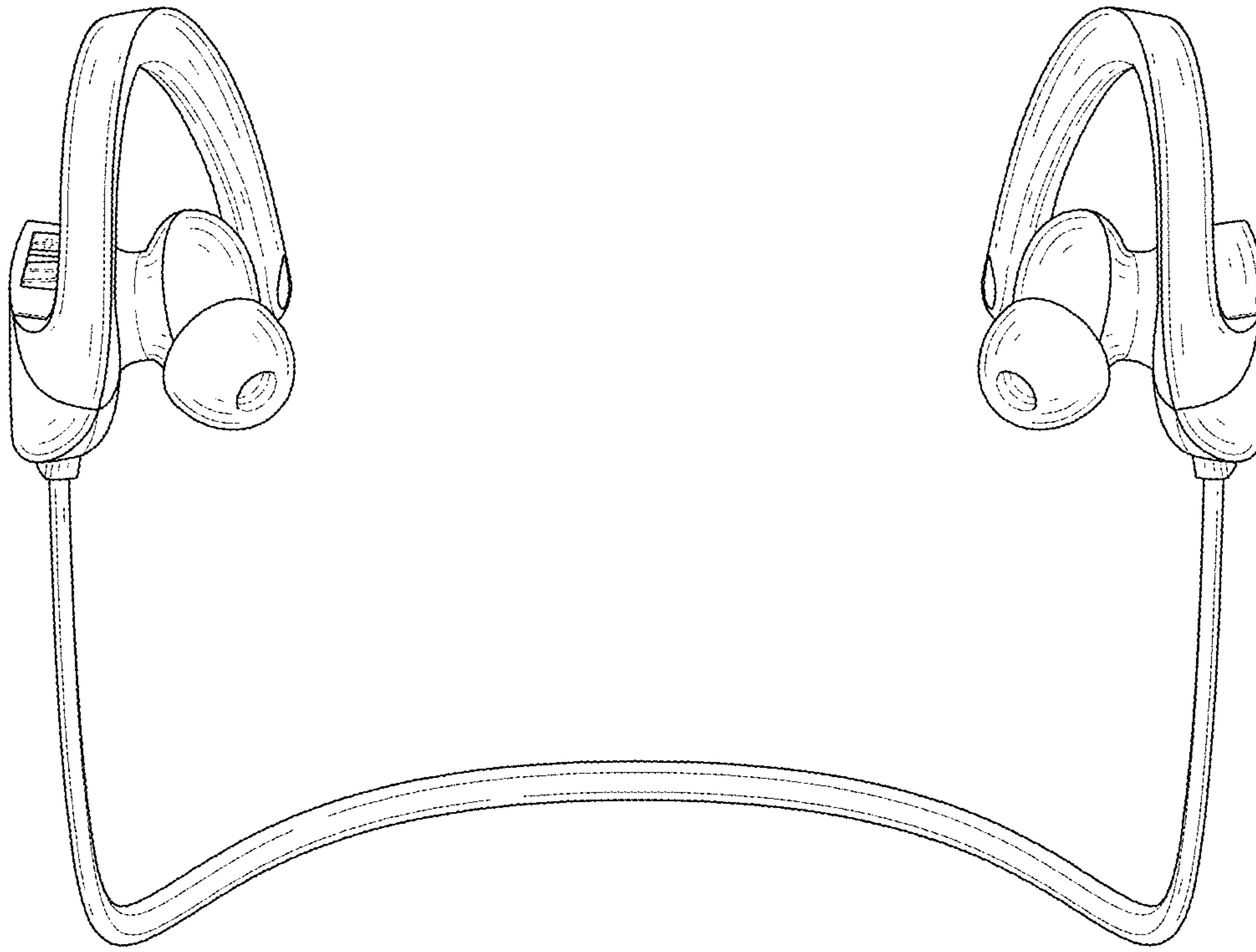


FIG. 3

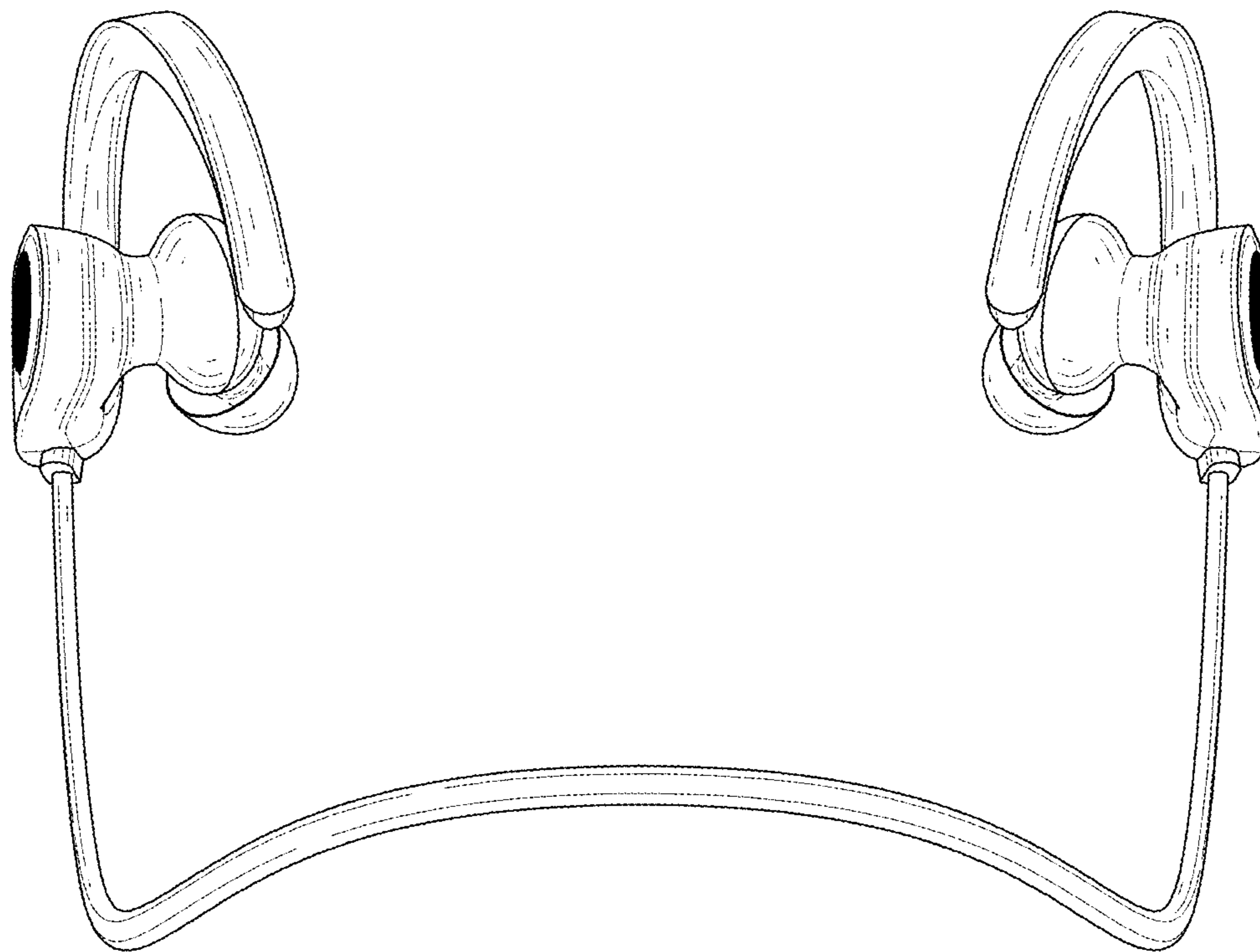


FIG. 4

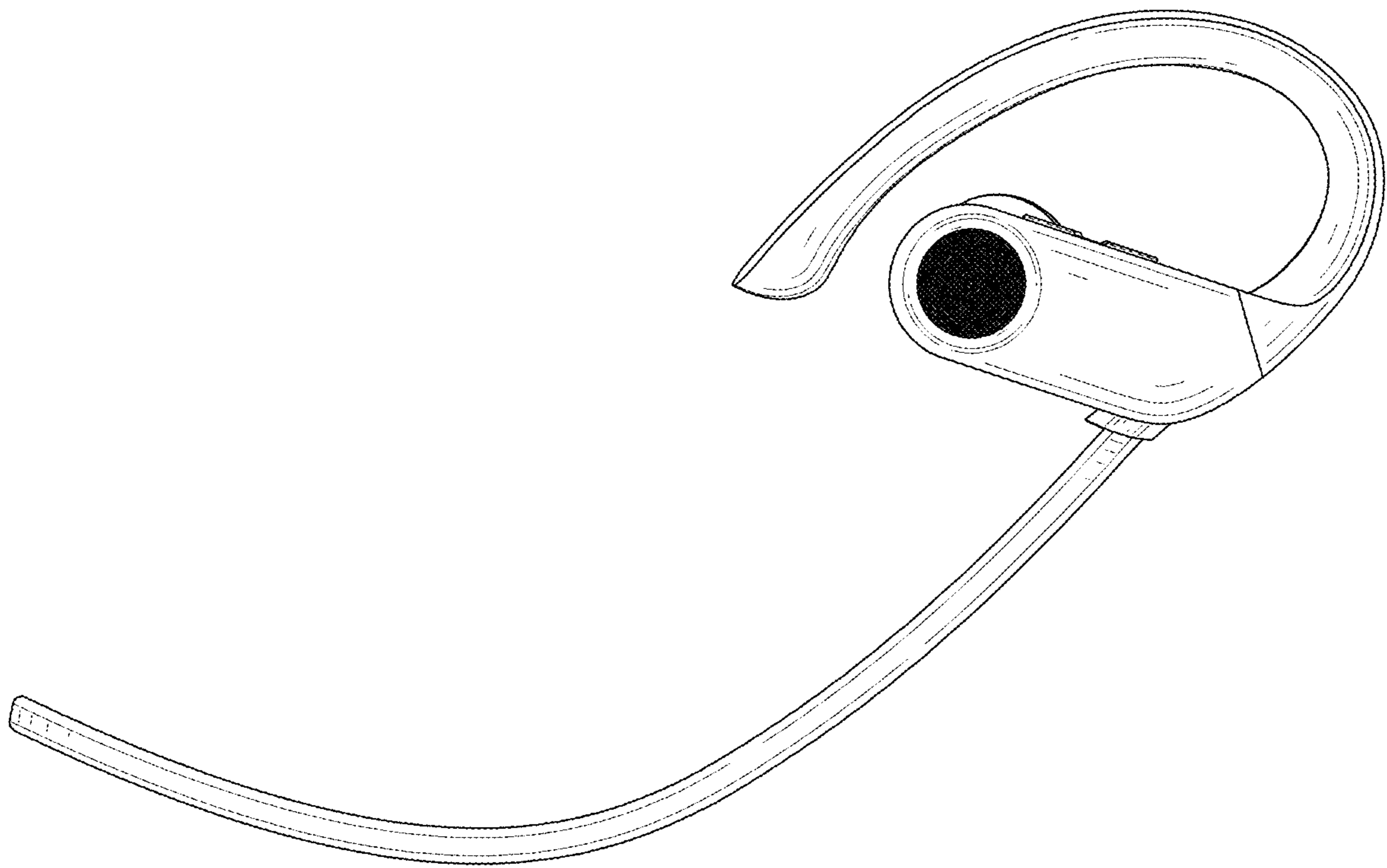


FIG. 5

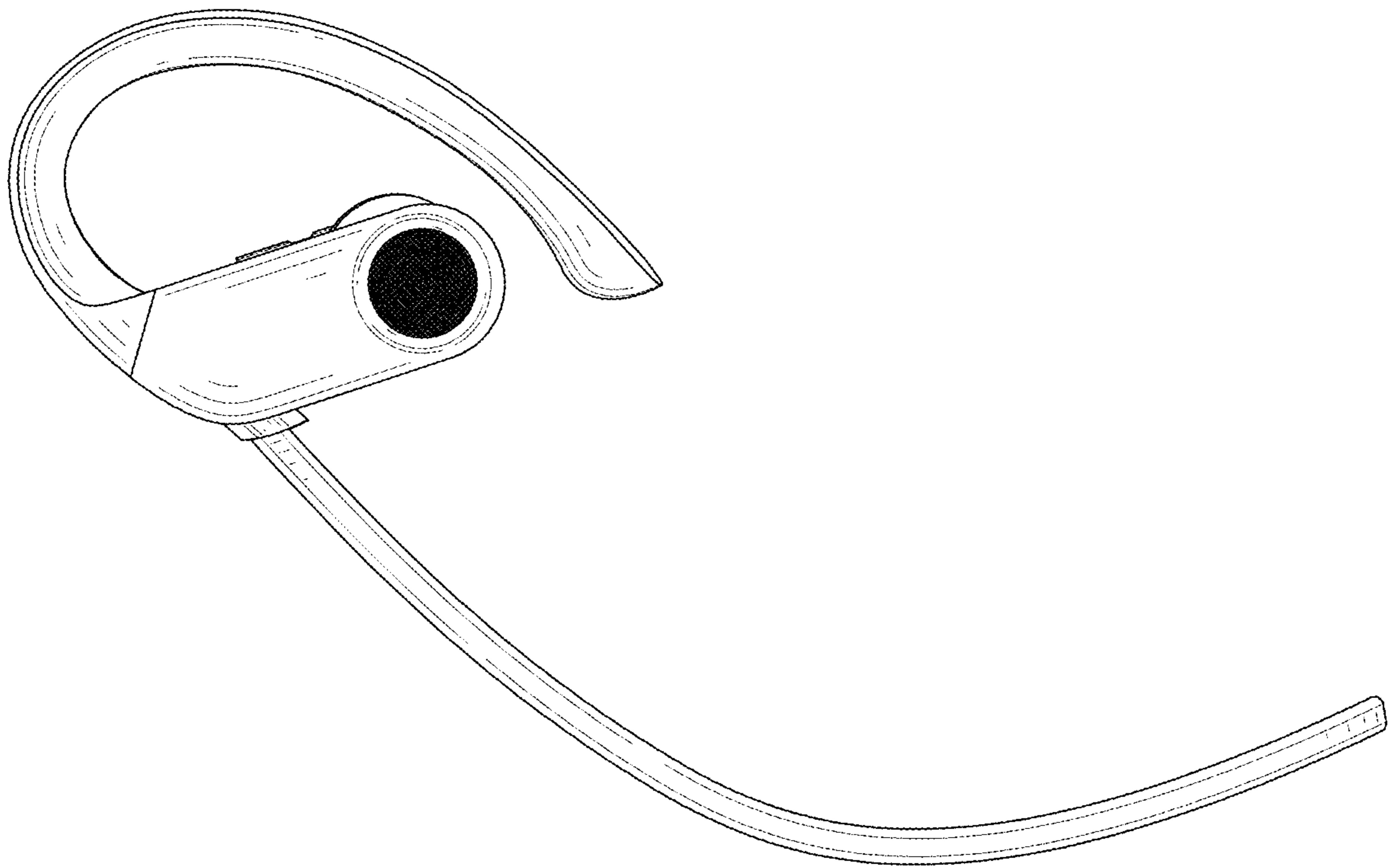


FIG. 6

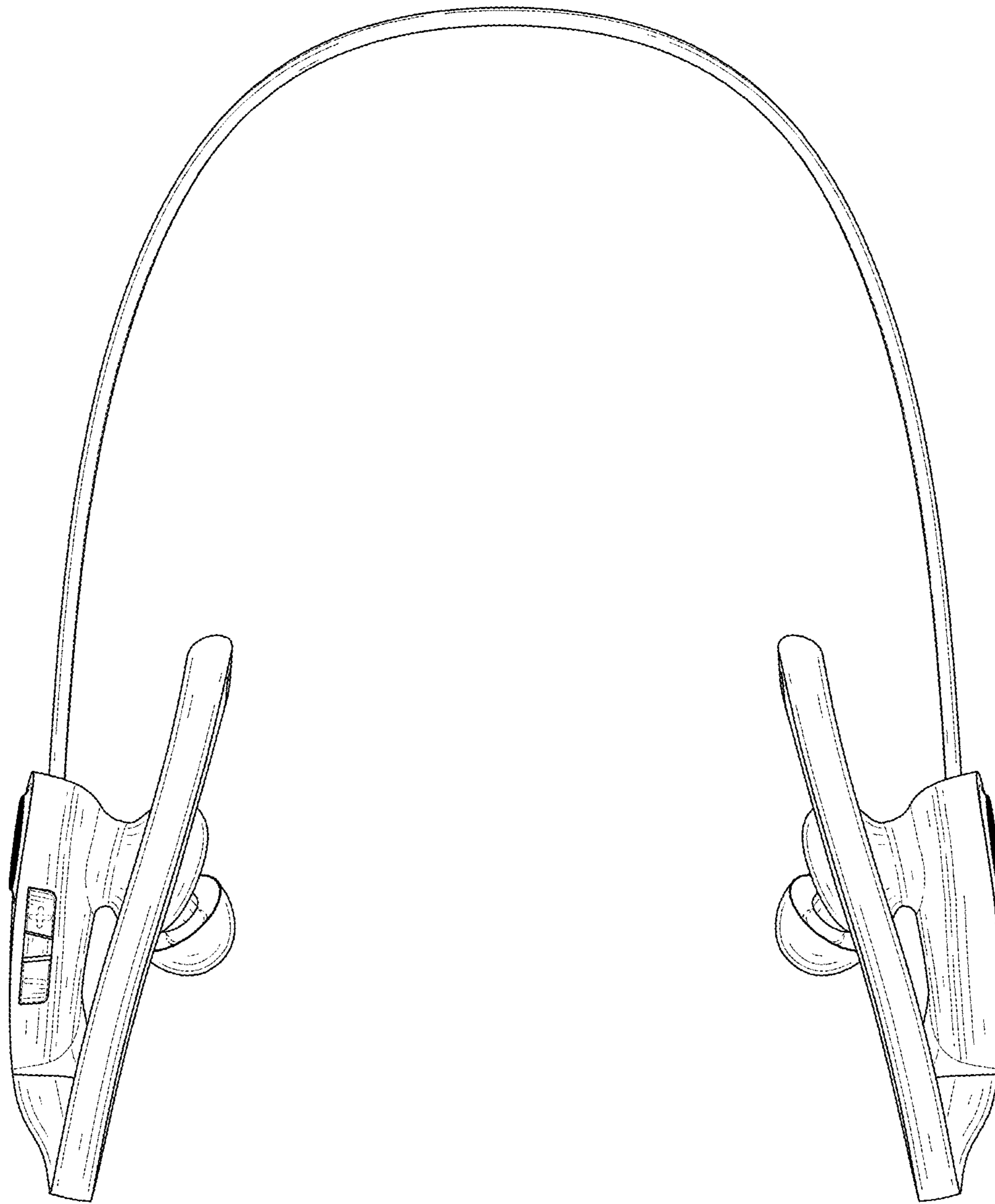


FIG. 7

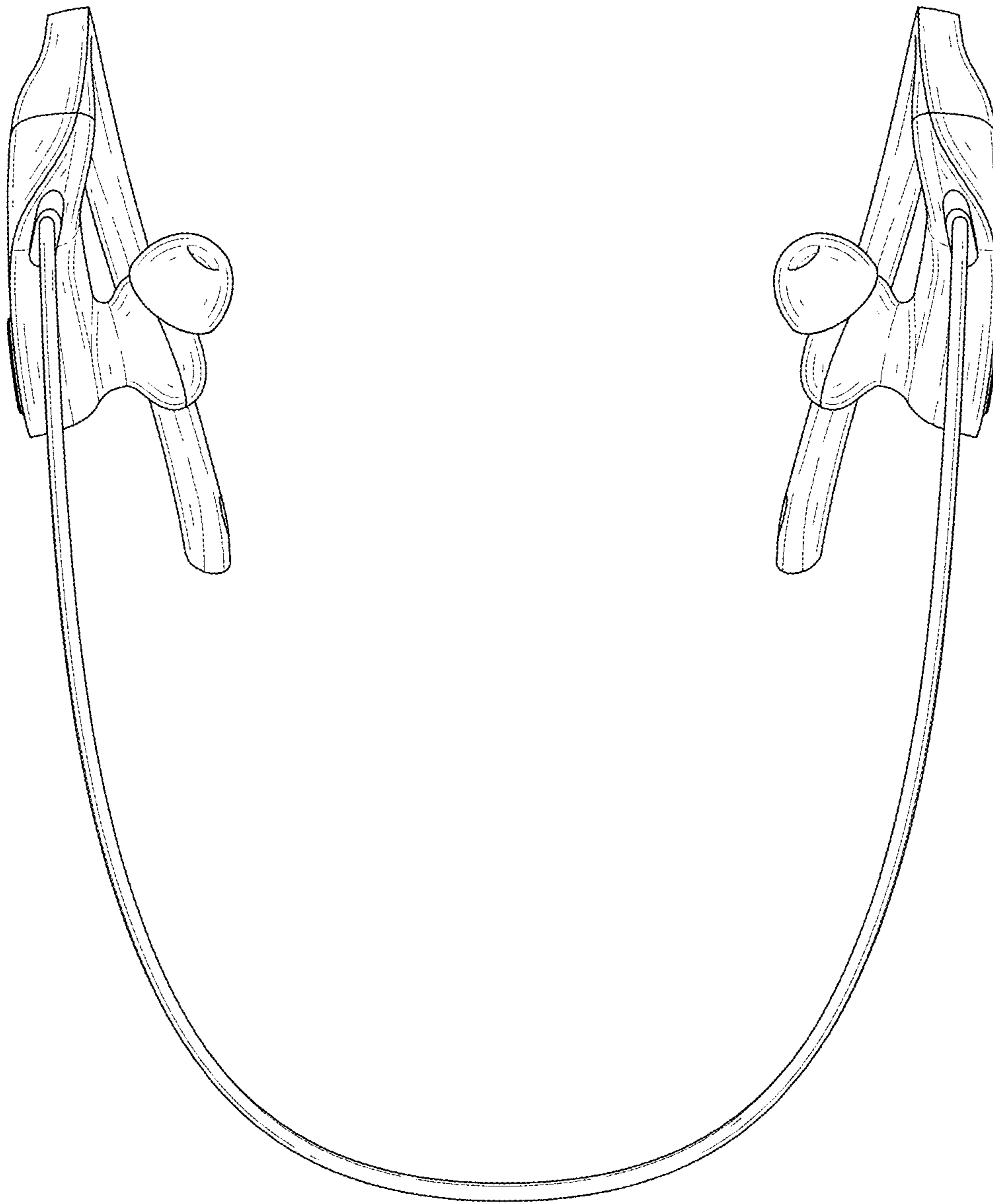


FIG. 8

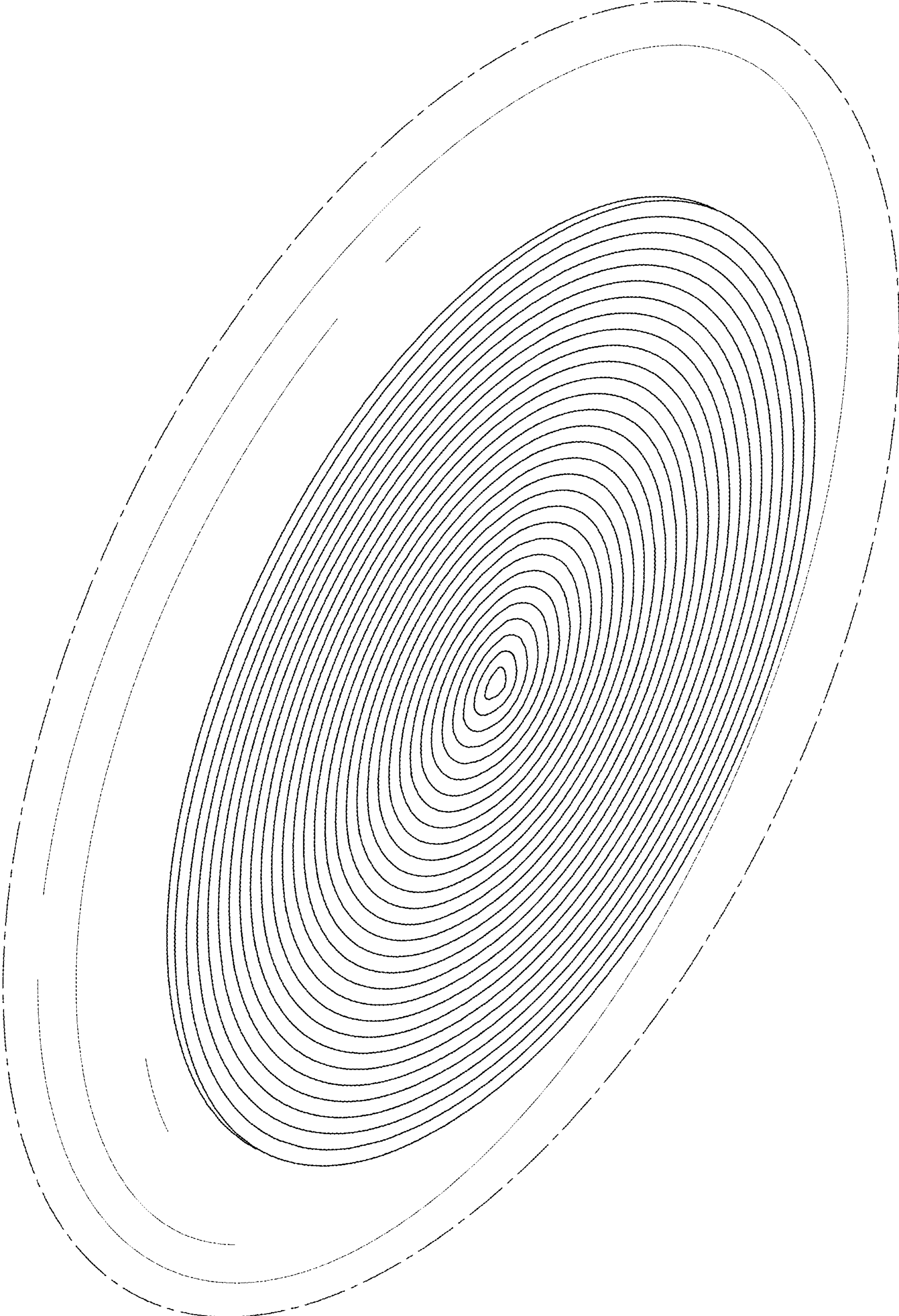


FIG. 9